

ABSTRACT

A bag opening method, a bag opening apparatus (S1), and a bag opening system (S) are provided. The bag opening method can open a protective bag (A1) of a semiconductor material (A). The semiconductor material (A) includes the protective bag (A1), an accommodating box (A2), and a tape (A3). The protective bag (A1) is configured to have a packaging portion (A13) and a non-packaging portion (A14), the packaging portion (A13) covers an outer periphery of the accommodating box (A2), the non-packaging portion (A14) is folded into a tail structure (A15), and the tape (A3) can fix the tail structure (A15) to the packaging portion (A13). The bag opening method includes a positioning step (S101), a first cutting step (S102), a pulling step (S103), and a second cutting step (S104).

Fig. 1